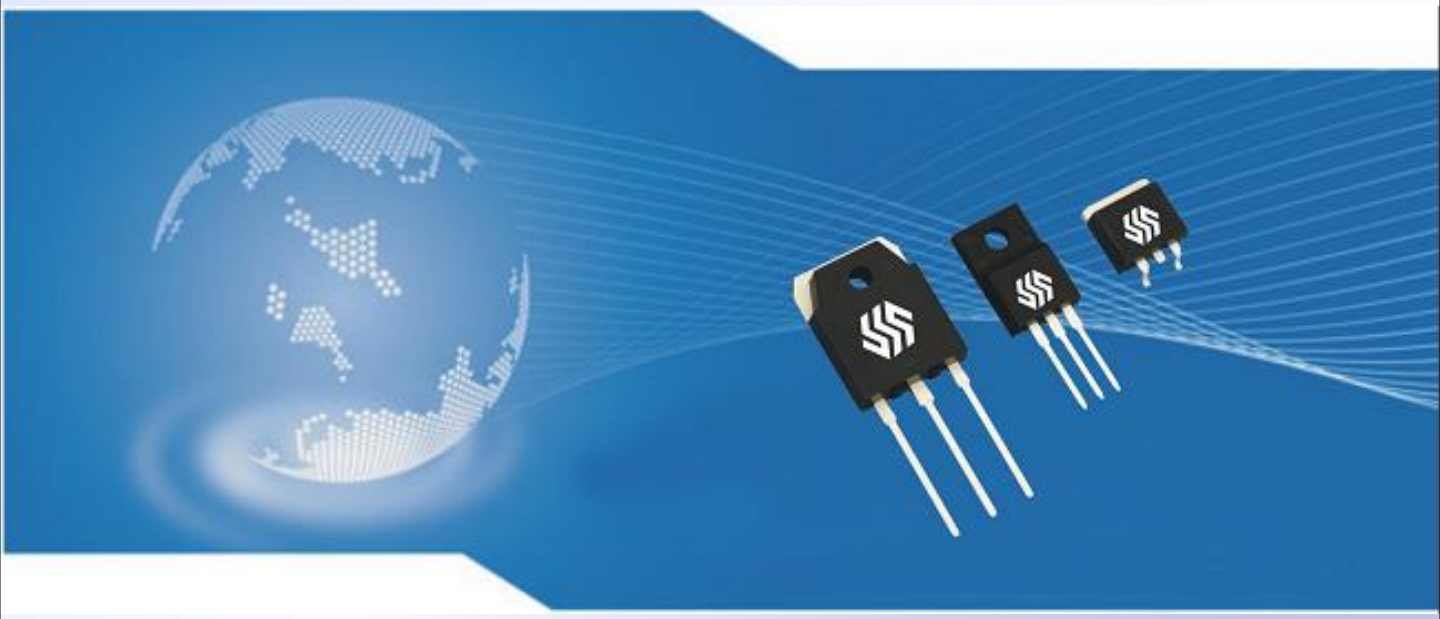
SUPER-SEMI



SUPER-MOSFET

Super Junction Metal Oxide Semiconductor Field Effect Transistor

500V Super Junction Power MOSFET With Fast-Recovery
SS*50R100SFD

Rev.1.0
Sep. 2019

www.supersemi.com.cn

March, 2016

SJ-FET

SSW50R100SFD/SSA50R100SFD
500V N-Channel MOSFET With Fast-Recovery

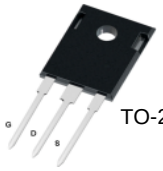
Description

SJ-FET is new generation of high voltage MOSFET family that is utilizing an advanced charge balance mechanism for outstanding low on-resistance and lower gate charge performance. This advanced technology has been tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy. SJ-FET is suitable for various AC/DC power conversion in switching mode operation for higher efficiency.

Features

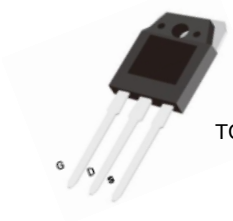
- Multi-Epi process SJ-FET
- Fast-Recovery body diode
- Extremely Low Reverse Recovery Charge
- 550V @TJ = 150 ℃
- Typ. RDS(on) = 90mΩ
- Ultra Low Gate Charge (typ. Qg = 45nC)
- 100% avalanche tested

SSW50R100SFD

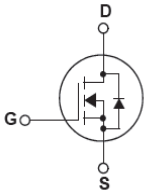


TO-247

SSA50R100SFD



TO-3P



Absolute Maximum Ratings

Symbol	Parameter	SSW_A50R100SFD	Unit
V_{DSS}	Drain-Source Voltage	500	V
I_D	Drain Current -Continuous (TC = 25℃) -Continuous (TC = 100℃)	33* 20*	A
I_{DM}	Drain Current - Pulsed (Note 1)	100	A
V_{GSS}	Gate-Source voltage	±30	V
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	780	mJ
I_{AR}	Repetitive Avalanche Current (Note 1)	9	A
E_{AR}	Repetitive Avalanche Energy (Note 1)	1	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	15	V/ns
dVds/dt	Drain Source voltage slope (Vds=400V)	50	V/ns
P_D	Power Dissipation (TC = 25℃)	284	W
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	℃
T_L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300	℃

* Drain current limited by maximum junction temperature. Maximum duty cycle D=0.75.

Thermal Characteristics

Symbol	Parameter	SSW_A50R100SFD	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.44	℃/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink Typ.	0.5	℃/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62	℃/W

Electrical Characteristics TC = 25℃ unless otherwise noted

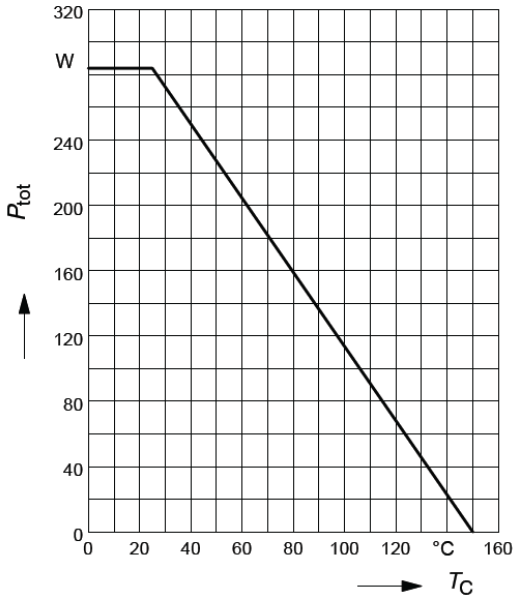
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0V, I_D = 250μA, T_J = 25℃	500	-	-	V
		V_{GS} = 0V, I_D = 250μA, T_J = 150℃	-	550	-	V
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temperature Coefficient	I_D = 250μA, Referenced to 25℃	-	0.6	-	V/℃
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 500V, V_{GS} = 0V -T_J = 150℃	-	1 300	5 -	μA μA
I_{GSSF}	Gate-Body Leakage Current, Forward	V_{GS} = 30V, V_{DS} = 0V	-	-	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	V_{GS} = -30V, V_{DS} = 0V	-	-	-100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 250μA	3.0	-	5.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	V_{GS} = 10V, I_D = 17A	-	90	105	mΩ
g_{FS}	Forward Transconductance	V_{DS} = 40V, I_D = 17A	-	25	-	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = 25V, V_{GS} = 0V, f = 1.0MHz	-	2100	-	pF
C_{oss}	Output Capacitance		-	850	-	pF
C_{rss}	Reverse Transfer Capacitance		-	13	-	pF
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = 400V, I_D = 17A R_G = 20Ω (Note 4)	-	42	-	ns
t_r	Turn-On Rise Time		-	9	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	150	-	ns
t_f	Turn-Off Fall Time		-	9	-	ns
Q_g	Total Gate Charge	V_{DS} = 400V, I_D = 17A V_{GS} = 10V (Note 4)	-	45	-	nC
Q_{gs}	Gate-Source Charge		-	10.5	-	nC
Q_{gd}	Gate-Drain Charge		-	16.5	-	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain-Source Diode Forward Current		-	-	33	A
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current		-	-	100	A
V_{SD}	Drain-Source Diode Forward Voltage	V_{GS} = 0V, I_S = 17A	-	0.9	1.5	V
t_{rr}	Reverse Recovery Time	V_{GS} = 0V, V_R = 400V, I_S = 15A, dI_F/dt =100A/μs	-	220	-	ns
Q_{rr}	Reverse Recovery Charge		-	1.6	-	μC
Irrm	Peak Reverse Recovery Current		-	14	-	A

NOTES:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. I_{AS}= 9A, VDD=50V, Starting TJ=25 ℃
3. I_{SD}≤ID, di/dt ≤ 200A/us, V_{DD} ≤ BV_{DSS}, Starting TJ = 25 ℃
4. Essentially Independent of Operating Temperature Typical Characteristics

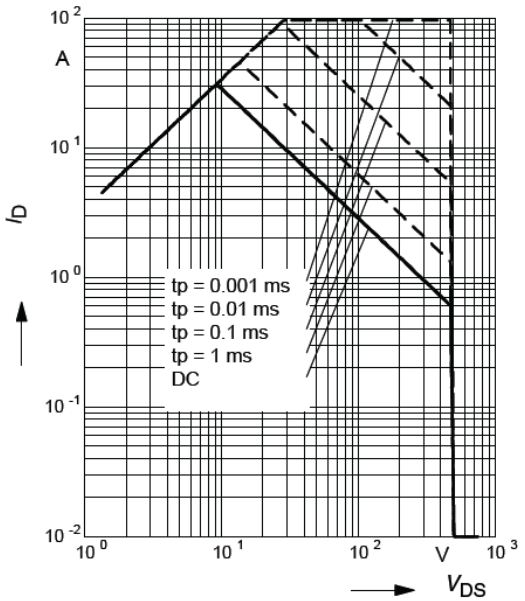
Typical Performance Characteristics

Power dissipation



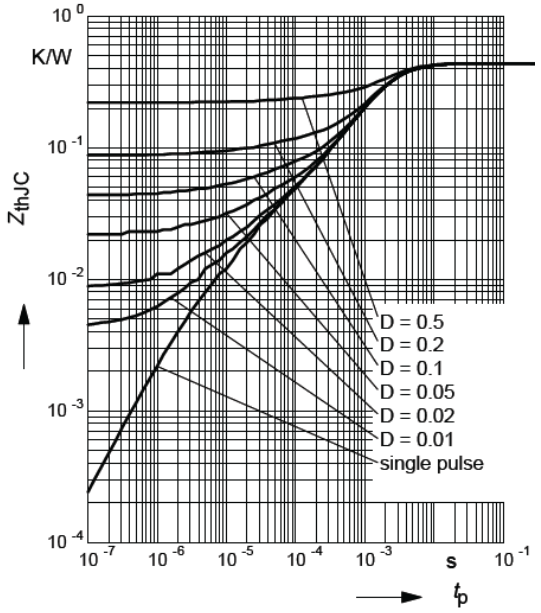
P_{tot}=f(T_C)

Safe operating area TC=25 ℃



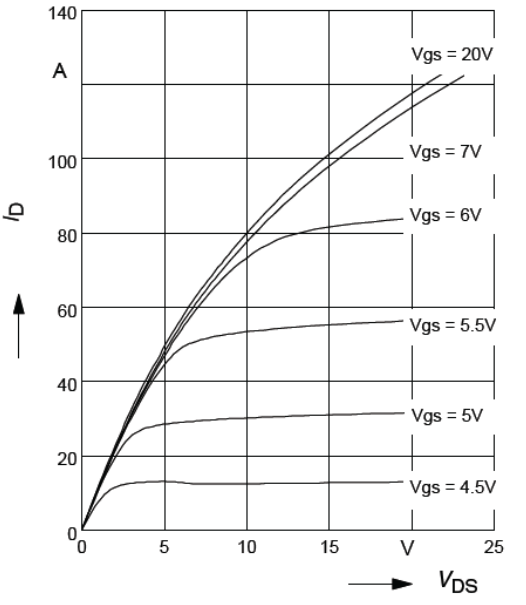
I_D=f(V_{DS}); T_C=25 ℃; D=0; parameter t_p

Max. transient thermal impedance



$Z_{(thJC)}$=f(tp); parameter D=tp/T

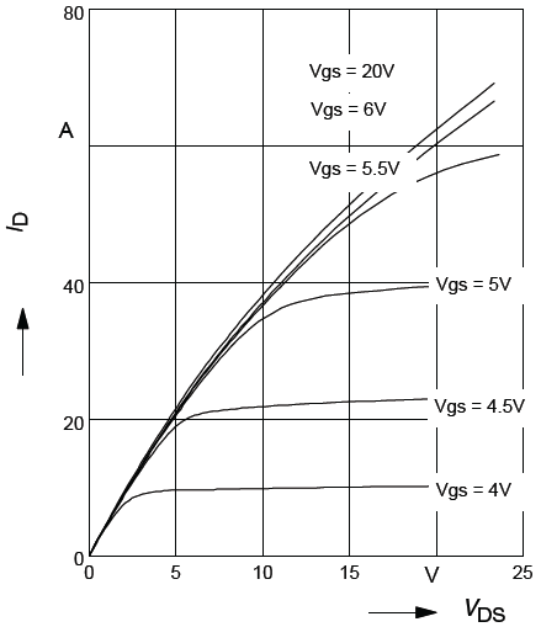
Typ. output characteristics T_j=25 ℃



I_D=f(V_{DS}); T_j=25 ℃ ; tp=10us
parameter: V_{GS}

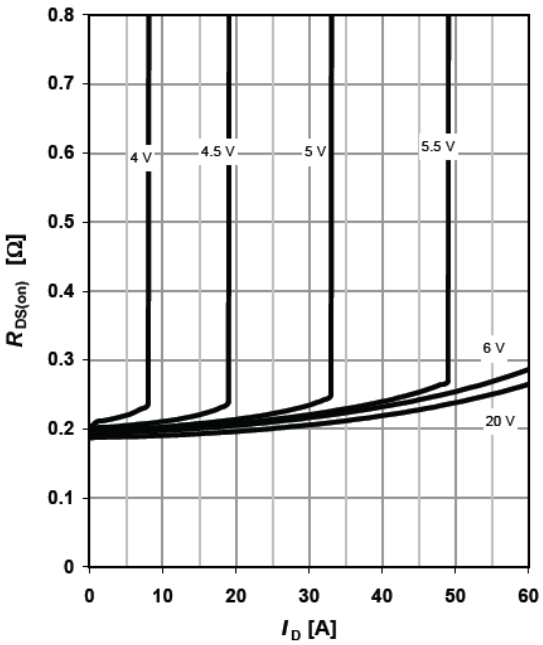
Typical Performance Characteristics

Typ. output characteristics T_j=125 ℃



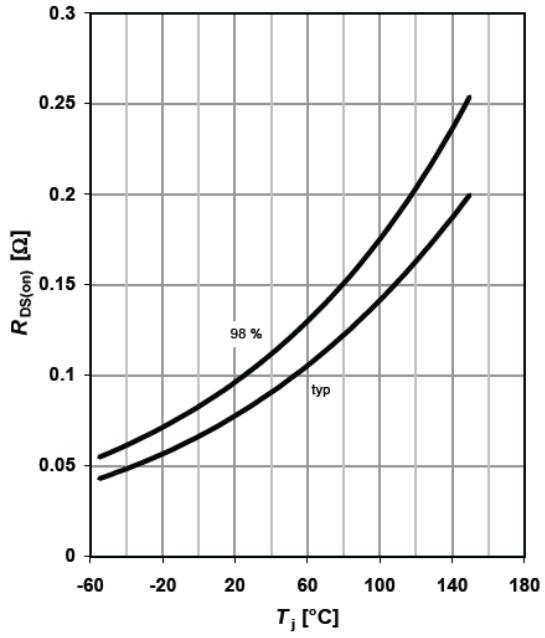
I_D=f(V_{DS}); T_j=125 ℃ ; tp=10us
parameter: V_{GS}

Typ. drain-source on-state resistance



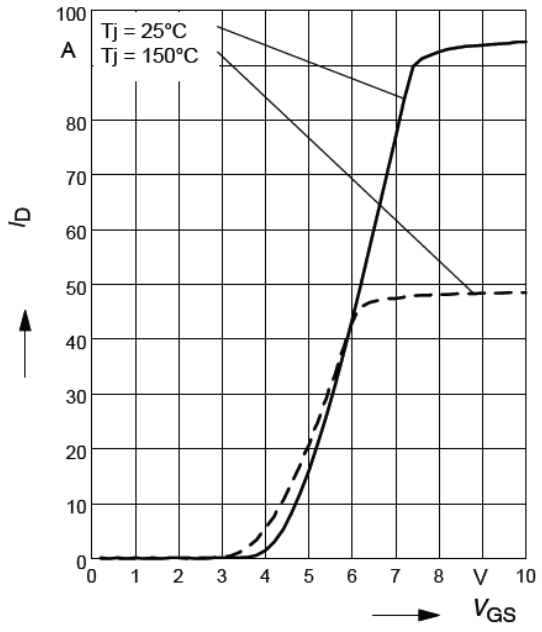
R_{DS}(on)=f(I_D); T_j=125 ℃ ; parameter:V_{GS}

Typ. drain-source on-state resistance



R_{DS}(on)=f(T_j); I_D=17 A; V_{GS}=10 V

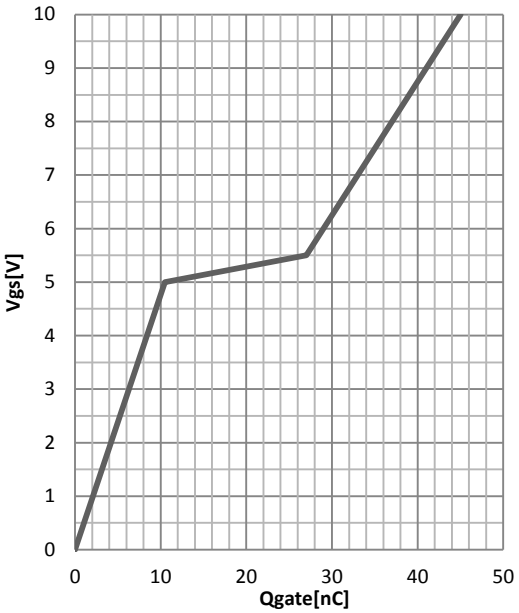
Typ. transfer characteristics



I_D=f(V_{GS}); V_{DS}=40V ; tp=10us

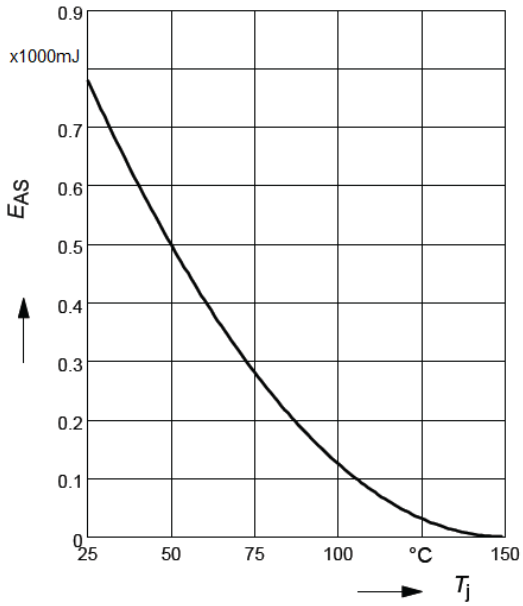
Typical Performance Characteristics

Typ. gate charge



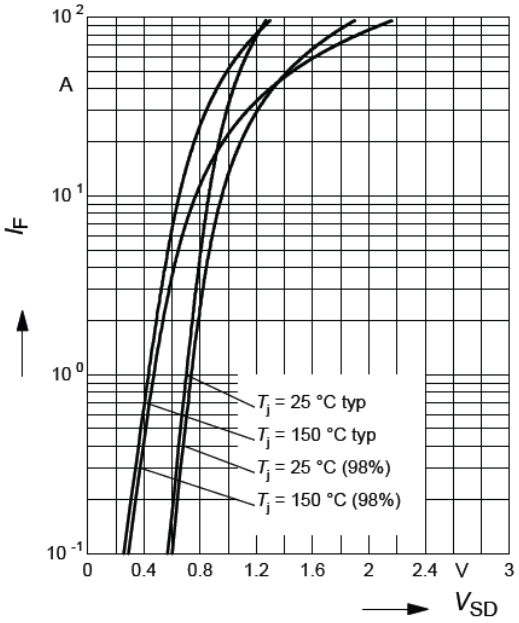
$V_{GS}=f(Q_g)$, $I_D=17A$ pulsed

Avalanche energy



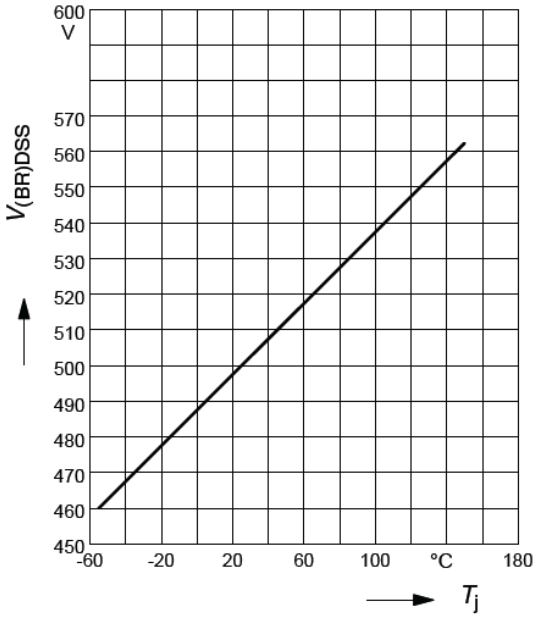
$E_{AS}=f(T_j)$; $I_D=9A$; $V_{DD}=50$ V

Forward characteristics of reverse diode



$I_F=f(V_{SD})$; tp=10us;
parameter: T_j

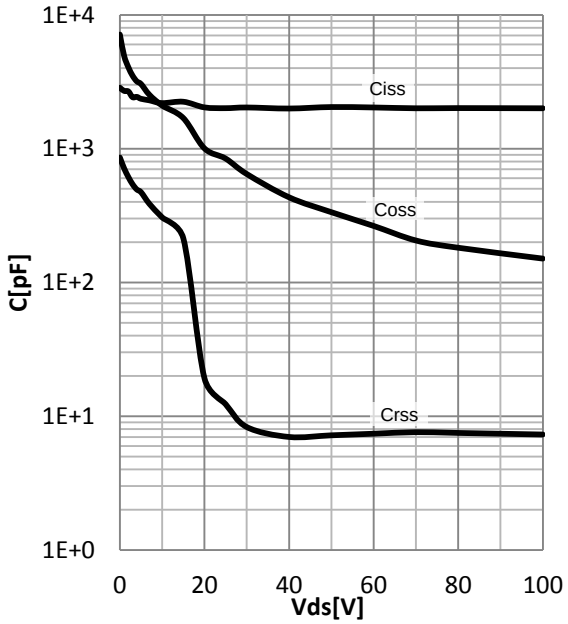
Drain-source breakdown voltage



$V_{BR(DSS)}=f(T_j)$; $I_D=0.25$mA

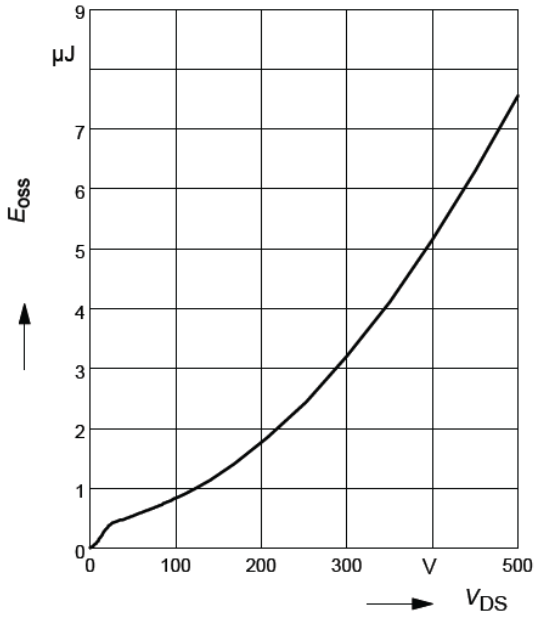
Typical Performance Characteristics

Typ. capacitances



$C=f(V_{DS})$; V_{GS}=0 V; f=1 MHz

Typ. Coss stored energy

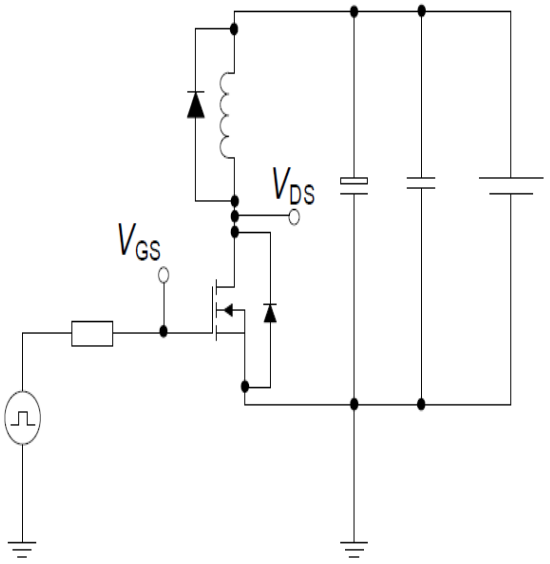


$E_{OSS}=f(V_{DS})$

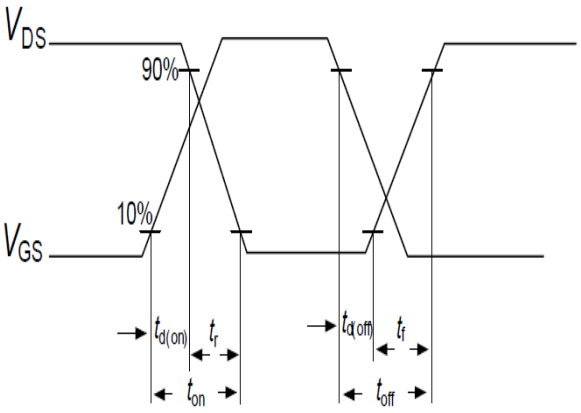
Test circuits

Switching times test circuit and waveform for inductive load

Switching times test circuit for inductive load

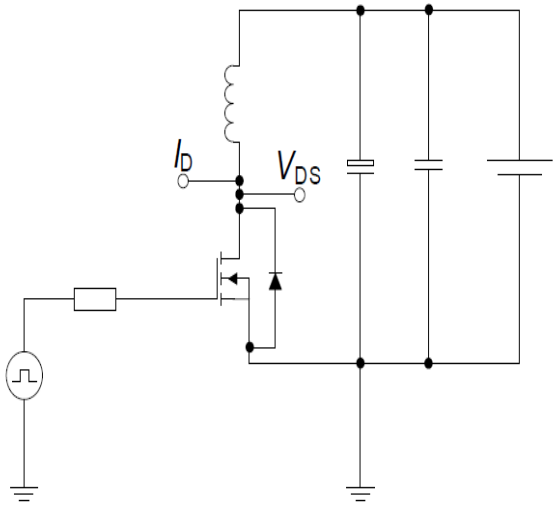


Switching time waveform

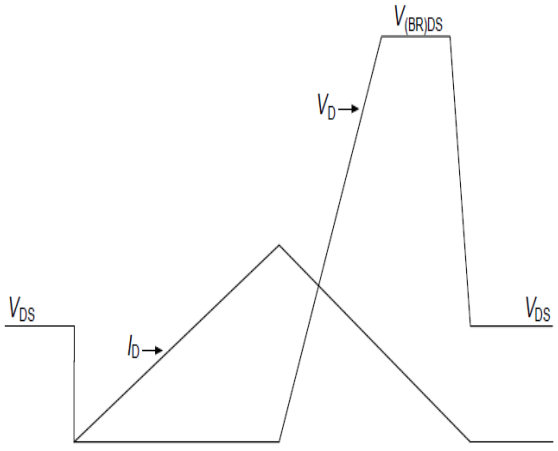


Unclamped inductive load test circuit and waveform

Unclamped inductive load test circuit



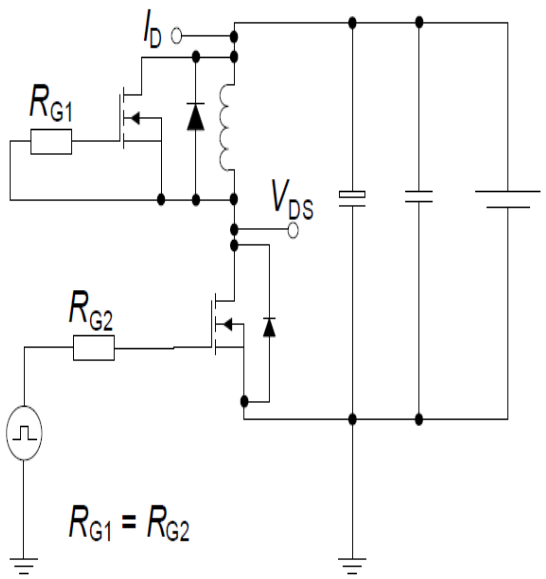
Unclamped inductive waveform



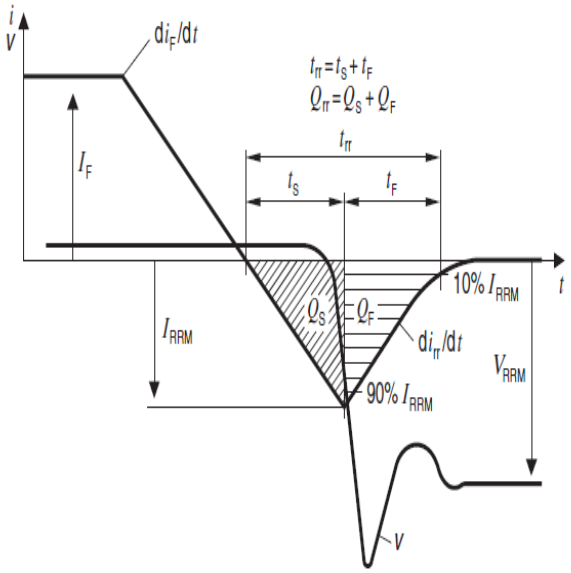
Test circuits

Test circuit and waveform for diode characteristics

Test circuit for diode characteristics

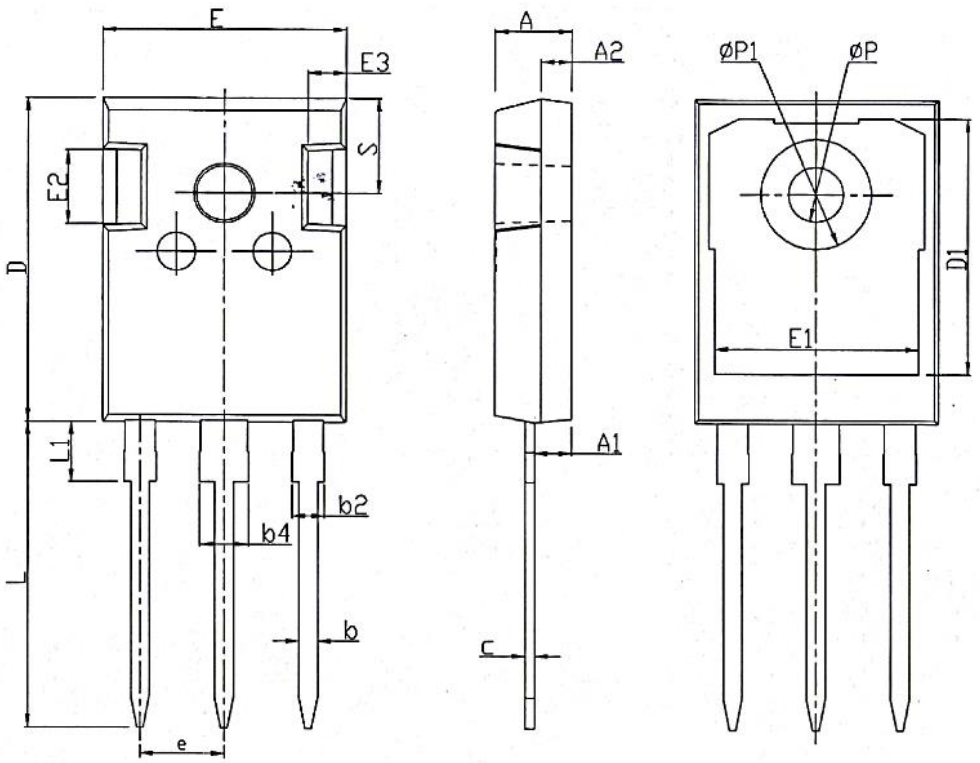


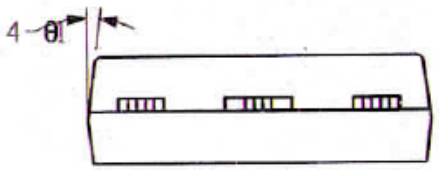
Diode recovery waveform



Package Outline

TO-247



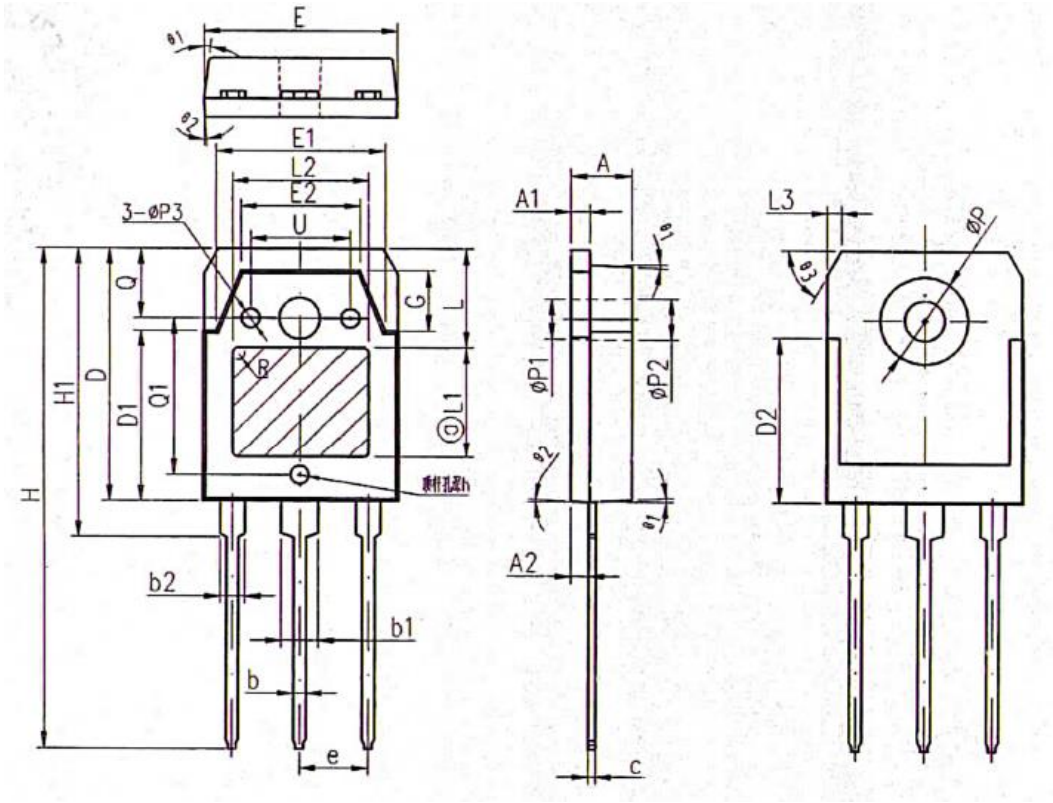


COMMON DIMENSIONS

SYMBOL	MM		
	MIN	NOM	MAX
A	4.90	5.00	5.10
A1	2.31	2.41	2.51
A2	1.90	2.00	2.10
b	1.16	1.21	1.26
b2	1.96	2.01	2.06
b4	2.96	3.01	3.06
c	0.59	0.61	0.66
D	20.90	21.00	21.10
D1	16.25	16.55	16.85
D2	1.05	1.20	1.35
E	15.70	15.80	15.90
E1	13.10	13.30	13.50
E2	4.90	5.00	5.10
E3	2.40	2.50	2.60
e		5.44BSC	
h	0.05	0.10	0.15
L	19.80	19.92	20.10
L1	-	-	4.30
ΦP	3.50	3.60	3.70
ΦP1	-	-	7.30
ΦP2	2.40	2.50	2.60
Q	5.60	5.80	6.00
S		6.15BSC	
R		0.50REF	
T	9.80	-	10.20
T1		1.65REF	
T2		8.00REF	
T3		12.80REF	
U	6.00	-	6.40
θ1	6°	7°	8°
θ2	4°	5°	6°
θ3	1°	-	1.5°
θ4	14°	15°	16°

Package Outline

TO-3P



COMMON DIMENSIONS

SYMBOL	MM		
	MIN	NOM	MAX
A	4.60	4.80	5.00
A1	1.40	1.50	1.60
A2	1.33	1.38	1.43
b	0.80	1.00	1.20
b1	2.80	3.00	3.20
b2	1.80	2.00	2.20
c	0.50	0.60	0.70
D	19.75	19.90	20.05
D1	13.70	13.90	14.10
D2	12.90REF		
E	15.40	15.60	15.80
E1	13.40	13.60	13.80
E2	9.40	9.60	9.80
e	5.45 TYP		
G	4.60	4.80	5.00
H	40.30	40.50	40.70
H1	23.20	23.40	23.60
h	0.05	0.10	0.15
L	7.40 TYP		
L1	9.00 TYP		
L2	11.00 TYP		
L3	1.00 REF		
ΦP	6.90	7.00	7.10
ΦP1	3.20 REF		
ΦP2	3.50 REF		
ΦP3	1.40	1.50	1.60
R	0.50 REF		
Q	5.00 REF		
Q1	12.56	12.76	12.96
U	7.8	8	8.2
θ1	5°	7°	9°
θ2	1°	3°	5°
θ3	60° REF		

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